

### IN THE SPECIFICATION

Please amend the specification as follows.

The paragraph beginning at page 1, after the title, is amended as follows:

#### Divisional Application

The present application is a divisional of application U.S. Serial No. 09/950,100, filed on September 10, 2001, now issued as U.S. Patent No. 6,671,172.

The paragraph beginning at page 1, line 10, is amended as follows:

#### Related Applications

The present application is related to the following applications which are assigned to the same assignee as the present application:

Serial No. 09/716,510, entitled “A High-Performance Fin Configuration For Air-Cooled Heat Dissipation Device[["],” now issued as U.S. Patent No. 6,633,484;

Serial No. 09/766,757, entitled “High-Performance Heat Sink Configurations For Use In High Density Packaging Applications[["],” now issued as U.S. Patent No. 6,535,385;

Serial No. 09/800,120, entitled “Radial Folded Fin Heat Sink”;

Serial No. 09/860,978 entitled “High Performance Air Cooled Heat Sinks Used In High Density Packaging Applications[["],” now issued as U.S. Patent No. 6,479,895;

Serial No. 10/047,101, entitled “Heat Sinks and Methods of Formation” (Client Docket P11461), now abandoned;

Serial No. 09/950,898, entitled “A Manufacturing Process for a Radial Fin Heat Sink” (Attorney Docket 884.443), ~~filed concurrently with the present application,~~ now issued as U.S. Patent No. 6,705,144; and

**AMENDMENT UNDER 37 C.F.R. 1.116 – EXPEDITED PROCEDURE**

Serial Number: 10/656,968

Filing Date: September 5, 2003

Title: Electronic Assemblies With High Capacity Heat Sinks and Methods of Manufacture

Assignee: Intel Corporation

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Dkt: 884.467US2 (INTEL)

Serial No. 09/950,101, entitled “Radial Folded Fin Heat Sinks and Methods of Making and Using Same” (Attorney Docket 884.468), ~~filed concurrently with the present application,~~  
now issued as U.S. Patent No. 6,657,862.